

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.60496	100.0	1.4
Subtotal				0.60496	100	1.4
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	1.59002	99.99	3.67963
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00016	0.01	0.00037
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
Subtotal				1.59018	100	3.68
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.012	0.03	0.02778
	Copper alloy	Iron (Fe)	7439-89-6	0.04001	0.1	0.0926
	Copper alloy	Copper (Cu)	7440-50-8	39.85377	99.6	92.2296
	Pure metal layer	Silver (Ag)	7440-22-4	0.10804	0.27	0.25002
Subtotal				40.01382	100	92.6
Adhesive	Polymer	Paraffin wax	8002-74-2	0.19791	20.0	0.458
	Polymer	Epoxy resin system		0.07916	8.0	0.1832
	Filler	Silver (Ag)	7440-22-4	0.71247	72.0	1.6488
Subtotal				0.98954	100	2.29
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	1.41982	2.5	3.28575
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.25946	7.5	9.85725
	Filler	Silica -amorphous-	7631-86-9	21.01335	37.0	48.6291
	Pigment	Carbon black	1333-86-4	0.28396	0.5	0.65715
	Polymer	Epoxy resin system		8.51893	15.0	19.7145
	Filler	Silicon Dioxide (SiO2)	14808-60-7	21.01335	37.0	48.6291
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.28396	0.5	0.65715
Subtotal				56.79283	100	131.43
Wire	Pure metal	Copper (Cu)	7440-50-8	0.00864	100.0	0.02
Subtotal				0.00864	100	0.02
Total				99.99997	100	231.42

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